

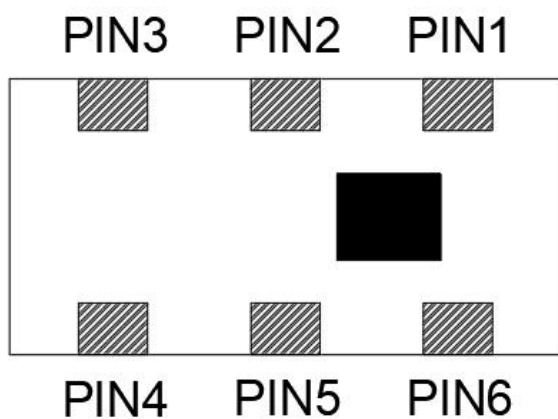
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

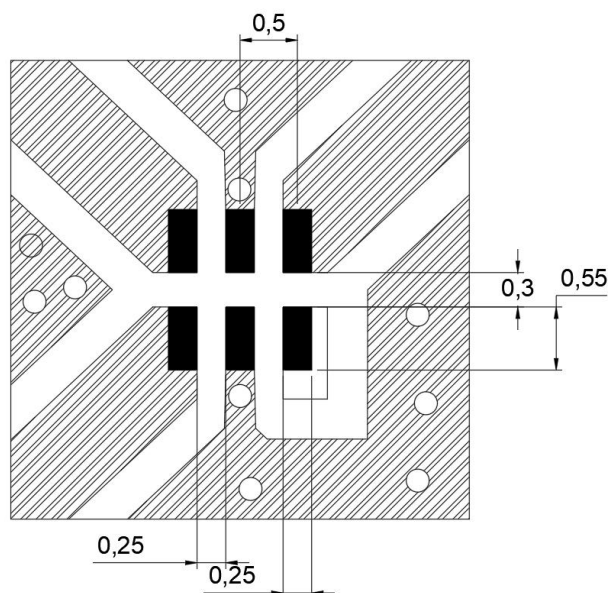
NO.	Parameter	SPEC
1	Frequency (MHz)	673~2700
2	Insertion Loss (dB)	2.0 max
3	VSWR	2.3 max
4	Amplitude balance (dB)	1.5 max
5	Impedance ratio	50;100
6	Phase balance (°)	180±15

Construction



PIN	Connection	PIN	Connection
1	Unbalanced Port	4	balanced Port
2	GND	5	GND
3	balanced Port	6	NC

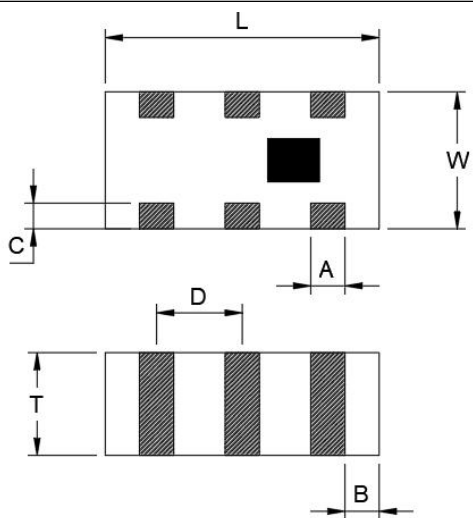
Mounting Considerations



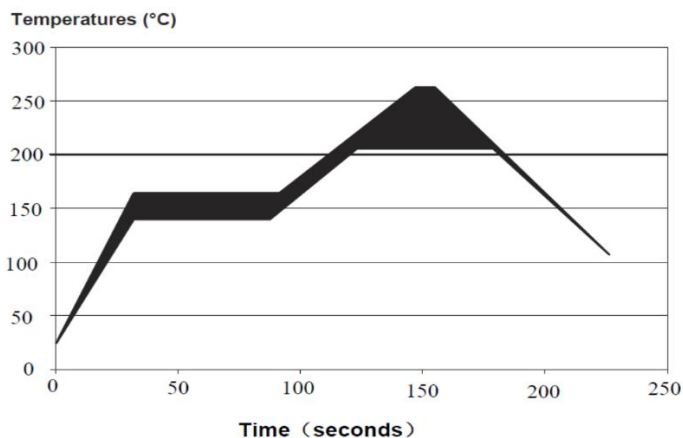
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.15
	W	0.80±0.15
	T	0.60±0.10
	A	0.20±0.10
	B	0.20±0.10
	C	0.15±0.10
	D	0.50±0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.